Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"6818553".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 09:49
S2		"20030160921".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2006/02/21 13:49
S3	1	S2 and (heat\$3 or thermal\$3 or rta or rtp or anneal\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/21 14:24
S4	645237	implant\$ or dop\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 08:32
S5	8320636	(viahole or opening or aperture or trench or hole or via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 11:39
S6	1430862	hydrogen or h2 or "h.sub.2"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 11:41
S8	15115	S4 with S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 14:26
S9	721	S8 with S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 14:29

S10	540	S9 and @ad<"20030401"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/02/22 08:11
S14	3021723	ch3 or "ch.sub.3" or ch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/22 08:42
S15	2233314	dielectric or insulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 08:43
S16	9880	S14 with S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/02/22 08:43
S17	516	S16 with (treat\$4 or expos\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/02/22 08:45
S18	153	S17 and @ad<"20031010"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/21 14:42
S19	2	"6790774".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 10:05
S20	3	(("20020022365") or ("6538324") or ("6333248")).PN.	US-PGPUB; USPAT	OR	OFF	2006/02/22 10:08
S21	4	(("20020022365") or ("6645852") or ("6538324") or ("6333248")).PN.	US-PGPUB; USPAT	OR	OFF	2006/02/22 11:00

S22	11	(("20050095751") or ("20050054195") or ("20040166676") or ("20030194857") or ("20030104692") or ("20010053592") or ("6861349") or ("6833321") or ("6703307") or ("6642146") or ("5990011")).PN.	US-PGPUB; USPAT	OR	OFF	2006/02/22 13:14
S23	6190	implant\$7 with barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 11:38
S24	1637	S23 and (copper or tungsten or cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 11:38
S25	1329	S24 and (damascene or viahole or opening or aperture or trench or hole or via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 11:40
S26	136	S24 and (damascene)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/02/22 11:39
S27	635	S25 and (stop\$4 or etchstop\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 11:40
S28	1430862	hydrogen or h2 or "h.sub.2"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/22 11:42
S29	307	S27 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON T	2006/02/22 11:55

S30	192	S29 and (semiconductor or (semi adj1 conductor))	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	ON	2006/02/22 12:26
S32	32	10/682196	DERWENT; IBM_TDB US-PGPUB;	OR	OFF	2007/03/21 09:27
			USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
S33	2	("6318124").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/21 09:52
S34	2	("5554570").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/21 09:52
S35	2	"770114".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/21 14:43
S36	2	"20010019857"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/21 14:43
S37	411	(hsq or hydrogensilsesquioxane or (hydrogen adj1 silsesquioxane)) near4 (dielectric near3 constant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 08:22
S38	683	(hsq or hydrogensilsesquioxane or (hydrogen adj1 silsesquioxane)) with (porous or nonporous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 08:37

S39	68	(hsq or hydrogensilsesquioxane or (hydrogen adj1 silsesquioxane)) with (hybrid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 08:38
S40	0	S39 and "20010019857"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 10:08
S41	29196	supercritical or (super adj1 critical)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 10:09
S42	.2	("6318124").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 10:09
S43	2 ·	"20010019857"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/23 10:09
S44	<b>4</b> *	S42 or S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 10:09
S45	0	S44 and S41	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 10:10
S46	32	10/682196 and S41	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 10:13

C47	202004	"oo oo b 2" oo (oo b	LIC BODIES	Too	055	2007/02/22 12
S47	393881	"co.sub.2" or (carbon adj1 dioxide) or (carbon adj1 di-oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 10:14
S48	10763	S41 with S47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/23 10:14
S49	1826013	semiconductor or (semi adj1 conductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/23 10:15
S50	1908	S48 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/23 10:15
S51	717	(dielectric or insulat\$4 or film or layer) with S48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/23 10:16
S52	394	S51 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/23 10:16
S53	229	S52 and @ad<"20031010"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 06:47
S54	0	(11/009575).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/25 06:48